

# 10 WATT POWER AMPLIFIER MODULE, 400 - 1000 MHz

## **Features**

P1dB Output Power: 10 Watts

Gain: 40 dB

Output IP3: +54 dBm Single Positive Supply: +12V

Thermally Compensated and Protected

TTL DC Power Enable Unconditionally Stable

Heat Sink/Fan Accessories Available

## **Typical Applications**

The HMC-C012 is ideal for:

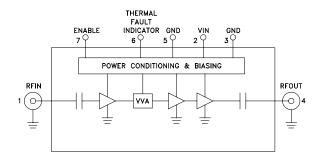
- Cellular/3G Infrastructure
- Automated Test Equipment (ATE)
- · Laboratory Use

## **General Description**

The HMC-C012 is a 10 Watt Power Amplifier Module suitable for Cellular/3G repeaters, wireless data, laboratory use and ATE applications. This extremely robust PA module is DC blocked, internally regulated and over voltage protected. Thermal protection/fault circuitry automatically turns off DC power if base temperature exceeds +75 °C and restores power at < +55 °C.



## **Functional Diagram**



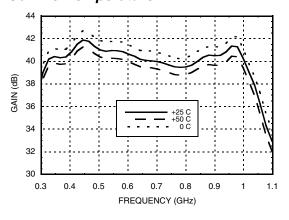
## Electrical Specifications, $T_A = +25^{\circ}$ C, VIN = +12V

Parameter	Min.	Тур.	Max.	Units
Frequency Range	0.4 - 1.0		GHz	
Gain	38	40		dB
Input Return Loss	9.5	12		dB
Output Return Loss	7.5	12		dB
Output Power for 1 dB Compression (P1dB)	9	10		W
Saturated Output Power (Psat)		42		dBm
Output Third Order Intercept (IP3) (Two-tone Input Power = -28 dBm each tone)		54		dBm
Channel Output Power for -60 dBc ACPR (CDMA-2000, 1.98 MHz offset)		36		dBm
Channel Output Power for -50 dBc ACPR (CDMA-2000, 885 kHz offset)		34		dBm
Second Harmonic at Output P1dB		-20		dBc
Third Harmonic at Output P1dB		-30		dBc
Spurious at Output P1dB		-65		dBc
Supply Current		6.5	7.0	Α

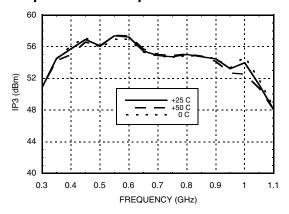


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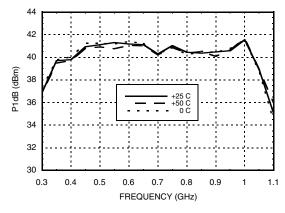
## Gain vs. Temperature



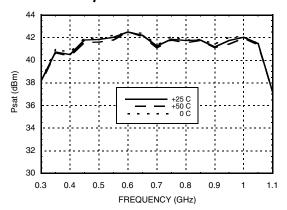
## Output IP3 vs. Temperature



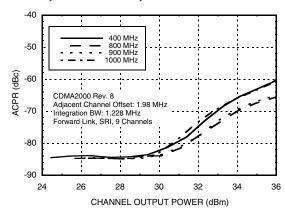
## P1dB vs. Temperature



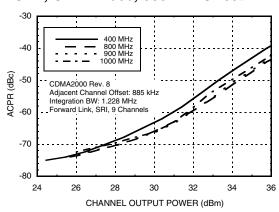
## Psat vs. Temperature



## ACPR, CDMA-2000, 1.98 MHz Offset



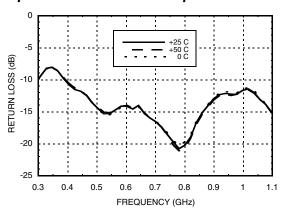
## ACPR, CDMA-2000, 885 kHz Offset



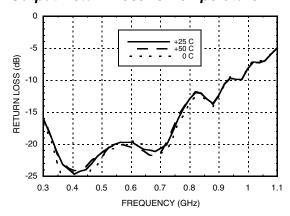


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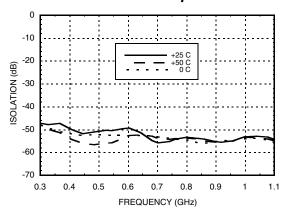
## Input Return Loss vs. Temperature



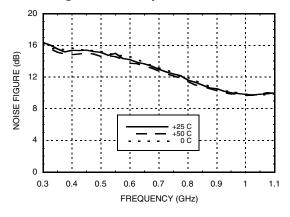
## **Output Return Loss vs. Temperature**



## Reverse Isolation vs. Temperature



## Noise Figure vs. Temperature



## **Absolute Maximum Ratings**

Supply Voltage (VIN)	+13 Vdc
RF Input Power (RFIN)	+10 dBm
Storage Temperature	-40 to +85 °C
Operating Temperature	0 to +50 °C
Thermal Fault Indicator Max Pdiss (derate 1.8 mW/°C above 50 °C)	180 mW
Enable	-0.5 to +6.0 Vdc

## Thermal Fault Indicator Characteristics

Parameter	Min.	Тур.	Max.	Units
I <sub>OUT</sub> (V <sub>OUT</sub> > 2V)		350		mA
$R_{ON}$ (I $OUT = 50$ mA)			7.5	Ohms
R <sub>OFF</sub> (V <sub>OUT</sub> = 30 V)		1		MOhm

# ELECTROSTATIC SENSITIVE DEVICE OBSERVE HANDLING PRECAUTIONS

## **Enable Input Characteristics**

Parameter	Min.	Тур.	Max.	Units
V <sub>IH</sub>	3.5			V
V <sub>IL</sub>			1.6	V
I <sub>IL</sub> @ VIN = 0V		-0.5		mA
I <sub>IH</sub> @ 5V		< ± 50		μΑ



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## **Recommended Biasing Procedure**

#### **TURN-ON**

- 1. Connect RF input and output
- 2. Apply Supply Voltage VIN (+12 Vdc)
- 3. Set Enable low
- 4. Apply RF input signal

## **TURN-OFF**

- 1. Remove RF input signal
- 2. Remove Supply Voltage VIN

## **Pin Descriptions**

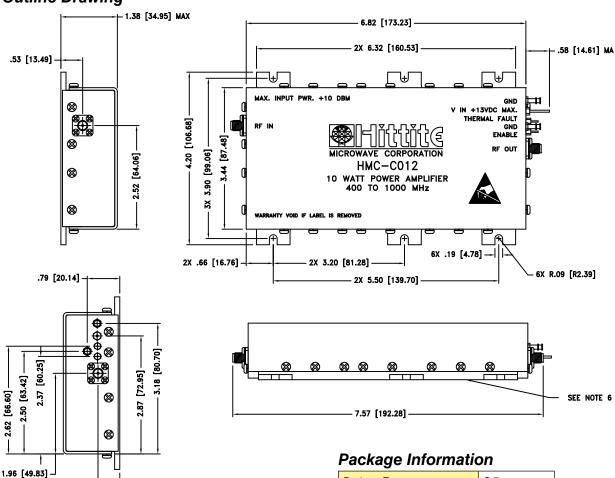
Pin Number	Function	Description	Interface Schematic
1	RFIN & RF Ground	RF input connector, SMA female. This pin is AC coupled and matched to 50 Ohms.	RFINO—  —
2	VIN	Power supply voltage for the amplifier.	VINO VOLTAGE REGULATOR
3	GND	Power supply ground.	⊖ GND =
4	RFOUT & RF Ground	RF output connector, SMA female. This pin is AC coupled and matched to 50 Ohms.	→   → RFOUT
5	GND	Ground for thermal fault indicator and enable circuit.	O GND =
6	Thermal Fault Indicator	Open drain output. High impedance for base plate temperatures less than 55 °C. Low impedance for base plate temperatures exceeding 75 °C.	
7	Enable	TTL compatible supply voltage (VIN) shutdown. If enable feature is not required, short this pin to DC ground.  TTL "High" Disable  TTL "Low" Enable	3.3K \( \triangle \)

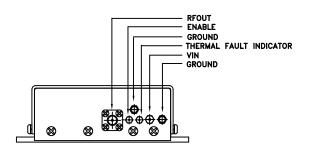


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## **Outline Drawing**

5X .53 [13.49]





Package Type	C-7	
Package Weight [1]	740 gms <sup>[2]</sup>	
Spacer Weight	N/A	

- [1] Includes the connectors
- [2] ±10% Tolerance

## NOTES:

- 1. MATERIAL: ALUMINUM 6061-T6
- 2. FINISH
- a. COVER & END PLATES, CHEMICAL FILM PER MIL-C-5541, CLASS 3
- b. BASE, TIN
- 3. RF CONNECTORS, SMA STYLE
- 4. DIMENSIONS ARE INCHES (MM)
- 5. TOLERANCES .X±.1 (2.54mm)

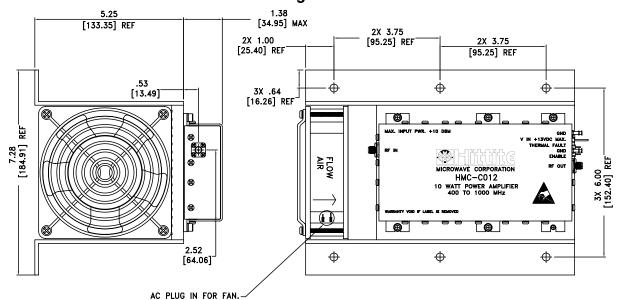
.XX±.02 (0.50mm)

- 6. DRAWING TO CHANGE AS REQUIRED.
- 7. BASE MUST BE GROUNDED AND MOUNTED TO HEAT SINK CAPABLE OF DISSIPATING 100W (65  $^{\circ}\text{C})$



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## HMC-C012 Heatsink/Fan Outline Drawing



## NOTES:

- 1. MATERIAL: ALUMINUM 6061-T6
- 2. FINISH: COVER & END PLATES, CHEMICAL FILM PER MIL-C-5541, CLASS 3
- 3. RF CONNECTORS, SMA STYLE
- 4. DIMENSIONS ARE INCHES (MM)
- 5. TOLERANCES .X±.1 (2.54mm)

.XX±.02 (0.50mm)

# 9.50 [241.30] REF 9.79 [248.67] REF

## **HMC-C008 Ordering Information**

Part Number	Description
HMC-C012	10 Watt Power Amplifier Module, 400 - 1000 MHz
HMC-C012HV115	10 Watt Power Amplifier Module with heat sink, 115 Vac fan and power cord.
HMC-C012HV230	10 Watt Power Amplifier Module with heat sink, 230 Vac fan and power cord.

